

Call for papers

ISTeSHE2026

THE 2ND INTERNATIONAL SYMPOSIUM OF TECHNICAL SAFETY,
OCCUPATIONAL HEALTH AND ENVIRONMENT 2026

23-24 SEPTEMBER 2026 (VIRTUAL)

"Transforming Occupational Safety, Health, and Environment Practices for a Resilient and Sustainable Future"

SCOPES

- Occupational Health
- Epidemiology & Occupational Disease
- Process Safety & Loss prevention
- Rehabilitation & Occupational Therapy
- Safety Engineering
- Technical Safety Forensics
- Safety, Health & Environmental Management
- Fire & Explosion Safety
- Industrial Hygiene
- Environmental Quality Control & Technology
- Human Engineering
- Emergency & Disaster Management Technology
- Artificial Intelligence for Occupational Safety, Health & Environment

PUBLICATION

- IIUM Medical Journal Malaysia (WOS Q4)
- Journal of Environmental Health/Jurnal Kesehatan Lingkungan (Scopus Q4)
- ASEAN Journal on Science and Technology for Development (Scopus Q4)
- Journal of Industrial Management (MyCite)
- Current Science and Technology (Google Scholar)

CONTACT INFORMATION

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IMPORTANT DATES

- Abstract Submission Deadline
15 April 2026
30 June 2026
- Notification of Acceptance
15 July 2026
- Full Paper Submission
31 July 2026
- Registration Deadline
31 July 2026

CONFERENCE FEE

INTERNATIONAL PARTICIPANT

Attendee	USD100
Presenter (Google Scholar)	USD150
Presenter (MyCite)	USD200
Presenter (Scopus Journal)	USD300
Presenter (WOS Journal)	USD400

LOCAL PARTICIPANT

Attendee	RM100
Presenter (Google Scholar)	RM300
Presenter (MyCite)	RM550
Presenter (Scopus Journal)	RM1000
Presenter (WOS Journal)	RM1500

All submitted papers will be published in the selected indexed journal, subject to a successful peer-review evaluation

 **Clarivate™**
Web of Science

 **Scopus®**

 **MYCITE**
malaysian citation index

 **Google Scholar**

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